

FORM PTO-1449	U.S. DEPARTMENT OF COMMERCE PATENT AND TRADEMARK OFFICE	ATTY. DOCKET NO. ELM/002 Cont. 4	APPLN. NO. 10/672,961
O I P E INFORMATION DISCLOSURE STATEMENT BY APPLICANT SEP 23 2004		APPLICANTS Glenn J. Leedy	CONF. NO. 9439
		FILING DATE September 26, 2003	GROUP ART UNIT 2811

**U.S. PATENT DOCUMENTS**

EXAMINER INITIAL	DOCUMENT NUMBER	DATE	NAME	CLASS	SUBCLASS	FILING DATE IF APPROPRIATE
ML	2,915,722	12/01/59	Foster	336	115	
	3,202,948	08/24/65	Farrand	336	115	
	3,559,282	02/02/71	Lesk	438	113	
	3,560,364	02/02/71	Burkhardt	324	207.12	
	3,602,982	09/07/71	Emmasingel	29	577	
	3,615,901	10/26/71	Medicus	148	11.5 R	
	3,716,429	02/13/73	Napoli et al.	156	17	
	3,777,227	12/14/73	Krishna et al.	257	578	
	3,868,565	02/25/75	Kuipers	324	207.26	
	3,922,705	11/25/75	Yerman	357	26	
	3,997,381	12/14/76	Wanlass	156	3	
	4,070,230	01/24/78	Stein	156	657	
	4,131,985	01/02/79	Greenwood et al.	29	580	
	4,142,004	02/27/79	Hauser, Jr. et al.	438	792	
	4,251,909	02/24/81	Hoeberechts	29	580	
	4,262,631	04/21/81	Kubacki	118	723MP	
	4,394,401	07/19/83	Shioya et al.	427	574	
	4,401,986	08/30/83	Trenkler et al.	340	870.32	
	4,416,054	11/22/83	Thomas et al.	29	572	
	4,500,905	02/19/85	Shibata	357	68	
	4,539,068	09/03/85	Takagi et al.	156	614	
	4,585,991	04/29/86	Reid et al.	324	158 P	
	4,612,083	09/16/86	Yasumoto et al.	156	633	
	4,617,160	10/14/86	Belanger et al.	264	40.1	
	4,618,397	10/21/86	Shimizu et al.	156	628	
WU	4,618,763	10/21/86	Schmitz	250	211R	
ML	4,663,559	05/05/87	Christensen	313	336	

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ML	4,684,436	08/04/87	Burns et al.	216	65	
	4,693,770	09/15/87	Hatada	156	151	
	4,702,336	10/27/87	Maeda et al.	180	197	
	4,702,936	10/27/87	Seibert et al.	427	583	
	4,706,166	11/10/87	Go	361	403	
	4,721,938	01/26/88	Stevenson	338	4	
	4,761,681	08/02/88	Reid	357	68	
	4,784,721	11/15/88	Holmen et al.	156	647	
	4,810,673	03/07/89	Freeman	438	386	
	4,825,277	04/25/89	Mattox et al.	257	639	
	4,857,481	08/15/89	Tam et al.	438	619	
	4,892,753	01/09/90	Wang, et al.	427	579	
	4,897,708	01/30/90	Clements	257	690	
	4,924,589	05/15/90	Leedy	438	6	
	4,939,568	07/03/90	Kato, et al.	357	75	
ML	4,940,916	07/10/90	Borel et al.	313	306	
	Re B14,940,916	11/26/90	Borel et al.	315	306	
ML	4,950,987	08/21/90	Vranish et al.	324	207.23	
	4,952,446	08/18/90	Lee et al.	428	220	
	4,954,865	09/04/90	Rokos	257	378	
	4,957,882	09/18/90	Shinomiya	438	65	
	4,965,415	10/23/90	Young et al.	200	83 N	
	4,966,663	10/30/90	Mauger	205	656	
	4,983,251	01/08/91	Haisma et al.	438	3	
	4,994,735	02/19/91	Leedy	324	158	
J	5,000,113	03/19/91	Wang, et al.	118	723	
ML	5,008,619	04/16/91	Keogh et al.	324	207.17	
	5,010,024	04/23/91	Allen et al.	438	659	

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WLC	5,020,219	06/04/91	Leedy	29	846	
	5,034,685	07/23/91	Leedy	324	158 F	
	5,070,026	12/03/91	Greenwald et al.	437	3	
	5,071,510	12/10/91	Findler et al.	156	647	
	5,098,865	03/24/92	Machado et al.	438	788	
	5,103,557	04/14/92	Leedy	29	832	
	5,110,373	05/05/92	Mauger	148	33.2	
	5,111,278	05/05/92	Eichelberger	357	75	
	5,116,777	05/26/92	Chan et al.	438	234	
	5,130,894	07/14/92	Miller	361	393	
	5,132,244	07/21/92	Roy	438	477	
	5,151,775	09/29/92	Hadwin	357	80	
	5,156,909	10/20/92	Henager, Jr. et al.	428	334	
	5,203,731	04/20/93	Zimmerman	445	24	
	5,225,771	07/06/93	Leedy	324	158	
	5,236,118	08/17/93	Bower et al.	228	193	
	5,240,458	08/31/93	Linglain, et al.	464	63	
	5,259,247	11/09/93	Bantien	73	718	
	5,262,351	11/16/93	Bureau et al.	437	183	
	5,270,261	12/14/93	Bertin et al.	437	209	
	5,273,940	12/28/93	Sanders	437	209	
	5,274,270	12/28/93	Tuckerman	257	758	
	5,279,865	01/18/94	Chebi et al.	427	574	
	5,284,796	02/08/94	Nakanishi et al.	437	183	
	5,323,035	06/21/94	Leedy	257	48	
	5,324,687	06/28/94	Wojnarowski	437	225	
WLC	5,354,695	10/11/94	Leedy	438	411	

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EXAMINER INITIAL	DOCUMENT NUMBER	DATE	NAME	CLASS	SUBCLASS	FILING DATE IF APPROPRIATE
	5,363,021	11/08/94	MacDonald	315	366	
	5,385,632	01/31/95	Goossen	156	630	
	5,385,909	01/31/95	Nelson et al.	514	291	
	RE 34,893	04/04/95	Fujii et al.	257	419	
	5,420,458	05/30/95	Shimoji	257	622	
	5,424,920	06/13/95	Miyake	361	735	
	5,426,072	06/20/95	Finnila	437	208	
	5,426,363	06/20/95	Akagi et al.	324	239	
	5,432,444	07/11/95	Yasohama et al.	324	240	
	5,432,729	07/11/95	Carson et al.	365	63	
	5,434,500	07/18/95	Hauck et al.	324	67	
	5,451,489	09/19/95	Leedy	430	313	
	5,453,404	09/26/95	Leedy	437	203	
	5,457,879	10/17/95	Gurtler et al.	29	895	
	5,476,813	12/19/95	Naruse	437	132	
	5,489,554	02/06/96	Gates	437	208	
	5,502,667	03/26/96	Bertin et al.	365	51	
	5,512,397	04/30/96	Leedy	430	30	
	5,527,645	06/18/96	Pati et al.	430	5	
	5,529,829	06/25/96	Koskenmaki et al.	428	167	
	5,534,465	07/09/96	Frye et al.	437	209	
	5,555,212	09/10/96	Toshiaki et al.	365	200	
	5,563,084	10/08/96	Ramm et al.	437	51	
	5,571,741	11/05/96	Leedy	437	51	
	5,580,687	12/03/96	Leedy	430	5	
	5,581,498	12/03/96	Ludwig et al.	365	63	
	5,582,939	12/10/96	Pierrat	430	5	

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M	5,583,688	12/10/96	Hornbeck	359	291	
	5,592,007	01/07/97	Leedy	257	347	
	5,592,018	01/07/97	Leedy	257	619	
	5,595,933	01/21/97	Heijboer	439	20	
	5,606,186	02/25/97	Noda	257	226	
	5,627,112	05/06/97	Tennant et al.	438	113	
	5,629,137	05/13/97	Leedy	430	313	
	5,633,209	05/27/97	Leedy	435	228	
	5,637,536	06/10/97	Val	438	686	
	5,654,127	08/05/97	Leedy	430	315	
	5,654,220	08/05/97	Leedy	438	25	
	5,656,552	08/12/97	Hudak et al.	438	15	
	5,675,185	10/07/97	Chen et al.	257	774	
	5,694,588	12/02/97	Ohara et al.	395	566	
	5,725,995	03/10/98	Leedy	430	315	
	5,750,211	05/12/98	Weise et al.	427	579	
	5,760,478	06/02/98	Bozso et al.	257	777	
	5,773,152	06/30/98	Okonogi	428	446	
	5,786,116	07/28/98	Rolfson	430	5	
	5,793,115	08/11/98	Zavracky et al.	257	777	
	5,831,280	11/03/98	Ray	257	48	
	5,834,334	11/10/98	Leedy	438	107	
	5,840,593	11/24/98	Leedy	438	6	
	5,856,695	01/05/99	Ito et al.	257	370	
	5,868,949	02/09/99	Sotokawa et al.	216	18	
	5,869,354	02/09/99	Leedy	438	110	
VNL	5,870,176	02/09/99	Sweatt et al.	355	53	
VNL	5,880,010	03/09/99	Davidson	438	455	

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W	5,882,532	03/16/99	Field et al.	216	2	
	5,902,118	05/11/99	Hübner	438	106	
	5,915,167	06/22/99	Leedy	438	108	
	5,946,559	08/31/99	Leedy	438	157	
	5,985,693	11/16/99	Leedy	438	107	
	5,998,069	12/07/99	Cutter et al.	430	5	
	6,008,126	12/28/99	Leedy	438	667	
	6,020,257	02/01/00	Leedy	438	626	
	RE 36,623	03/21/00	Wang, et al.	427	579	
	6,045,625	04/04/00	Houston	148	33.3	
	6,084,284	07/04/00	Adamic, Jr.	257	506	
	6,087,284	07/11/00	Brix, et al.	501	69	
	6,097,096	08/01/00	Gardner et al.	257	777	
	6,133,640	10/17/00	Leedy	257	778	
	6,194,245 B1	02/27/01	Tayanaka	438	57	
	6,197,456 B1	03/06/01	Aleshin et al.	430	5	
	6,208,545 B1	03/27/01	Leedy	365	51	
	6,236,602 B1	05/22/01	Patti	365	201	
	6,261,728 B1	07/17/01	Lin	430	30	
	6,288,561 B1	09/11/01	Leedy	324	760	
	6,294,909 B1	09/25/01	Leedy	324	207.17	
W	6,518,073	02/11/03	Momohara	438	4	12/10/2001

**FOREIGN PATENT DOCUMENTS**

EXAMINER INITIAL	DOCUMENT NUMBER	DATE	COUNTRY	CLASS	SUBCLASS	TRANSLATION	
						YES	NO
	DE 32 33 195	03/1983	Germany				
W	JP 60-74643	04/1985	Japan				
W	JP S60-126871	07/1985	Japan				

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<u>ML</u>	EP 0 189 976	08/1986	EPO				
<u>ML</u>	JP S63-229862	09/1988	Japan				
<u>ML</u>	JP H01-199476	09/1988	Japan				
<u>ML</u>	2641129	12/1988	France				
<u>ML</u>	EP 0 314 437	05/1989	EPO				
<u>ML</u>	GB 2,215,168	09/1989	UK				
<u>ML</u>	JP 402027600A	01/1990	Japan				
<u>ML</u>	JP 02-082564	03/1990	Japan				
<u>ML</u>	JP H03-284871	12/1991	Japan				
<u>ML</u>	WO 92/03848	03/1992	PCT				
<u>ML</u>	JP 04-076946	03/1992	Japan				
<u>ML</u>	JP 04-083371	03/1992	Japan				
<u>ML</u>	JP 04-107964	04/1992	Japan				
<u>ML</u>	JP 04-196263	07/1992	Japan				
<u>ML</u>	EP 0 731 525	09/1996	EPO				
<u>ML</u>	WO 98/19337	05/1998	PCT				
<u>ML</u>	WO 01/05366	01/2001	PCT				

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<u>ML</u>	Scheuerman, R.J., "Fabrication of Thin Dielectric Films with Low Internal Stresses," J. Vac. Sci. and Tech., 7(1): 143-146 (1970).
<u>ML</u>	Bailey, R., "Glass for Solid-State Devices: Glass film has low intrinsic compressive stress for isolating active layers of magnetic-bubble and other solid-state devices," NASA Tech Brief (1982).
<u>ML</u>	Alloert, K., et al., "A Comparison Between Silicon Nitride Films Made by PCVD of N <sub>2</sub> -SiH <sub>4</sub> /Ar and N <sub>2</sub> -SiH <sub>4</sub> /He," Journal of the Electrochemical Society, Vol. 132, No. 7, pp. 1763-1766, (July 1985).
<u>ML</u>	Nguyen, S.V., "Plasma Assisted Chemical Vapor Deposited Thin Films for Microelectronic Applications, J. Vac. Sci. Technol. Vol. B4, No. 5, pp.1159-1167, (Sep/Oct. 1986).

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ML	Wolf, Stanley, "Basics of Thin Films," <i>Silicon Processing for the VLSI Era</i> , pp. 115, 192, 193, and 199 (1986).
ML	Knolle, W.R., et al., "Characterization of Oxygen-Doped, Plasma-Deposited Silicon Nitride," <i>Journal of the Electrochemical Society</i> , Vol. 135, No. 5, pp. 1211-1217, (May 1988).
ML	Olmer, et al., "Intermetal Dielectric Deposition by Plasma Enhanced Chemical Vapor Deposition," <i>Fifth IEEE/CHMT International Electronic Manufacturing Technology Symposium - Design-to-Manufacturing Transfer Cycle</i> , pp. 98-99 (1988).
ML	"Partitioning Function and Packaging of Integrated Circuits for Physical Security of Data," IBM Technical Disclosure Bulletin, IBM Corp.; 32(1): 46-49 (June 1989).
ML	Hsieh, et al., "Directional Deposition of Dielectric Silicon Oxide by Plasma Enhanced TEOS Process," 1989 Proceedings, Sixth International IEEE VLSI Multilevel Interconnection Conference, pp. 411-415 (1989).
ML	Runyan,W.R., "Deposition of Inorganic Thin Films," <i>Semiconductor Integrated Circuit Processing Technology</i> , p. 142 (1990).
ML	Hendricks, et al., "Polyquinoline Coatings and Films: Improved Organic Dielectrics for IC's and MCM's," <i>Eleventh IEEE/CHMT International Electronics Manufacturing Technology Symposium</i> , pp. 361-265 (1991).
ML	Tessier, et al., "An Overview of Dielectric Materials for Multichip Modules," SPE, Electrical & Electronic Div.; (6): 260-269 (1991).
ML	Treichel, et al., "Planarized Low-Stress Oxide/Nitride Passivation for ULSI Devices," J. Phys IV, Colloq. (France), 1 (C2): 839-846 (1991).
ML	Vossen, John L., "Plasma-Enhanced Chemical Vapor Deposition," <i>Thin Film Processes II</i> , pp. 536-541 (1991).
ML	Sze, S.M., "Surface Micromachining," <i>Semiconductor Sensors</i> , pp. 58-63 (1994).
ML	Krishnamoorthy, et al., "3-D Integration of MQW Modulators Over Active Submicron CMOS Circuits: 375 Mb/s Transimpedance Receiver -Transmitter Circuit," <i>IEEE Photonics Technology Letters</i> , 2(11): 1288-1290 (November 1995).
ML	Tielert, et al., "Benefits of Vertically Stacked Integrated Circuits for Sequential Logic," IEEE, XP-000704550, 121-124 (December 5, 1996).
ML	"IC Tower Patent: Simple Technology Receives Patent on the IC Tower, a Stacked Memory Technology," <a href="http://www.simpletech.com/whatsnew/memory/@60824.htm">http://www.simpletech.com/whatsnew/memory/@60824.htm</a> (1998).
ML	"Miniature Electron Microscopes Without Vacuum Pumps, Self-Contained, Microfabricated Devices with Short Working Distances, Enable Operation in Air," <i>NASA Tech Briefs</i> , 39-40 (1998).
	Partial European Search Report for Application No. EP 02009643 (October 8, 2002).

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